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12. (Amended) A method of manufacturing a semiconductor device comprising the steps of:

supporting a heat radiator placed in a cavity of a mold with at least one support pin;

placing a die pad of a lead frame to which a semiconductor chip is secured on the heat radiator;

closing the mold;

applying a pressure to the heat radiator by at least one support pin so as to cause a stress in the lead frame;

injecting a resin into the cavity from a resin injection port; and

pulling the support pin from the cavity into the mold before the resin is cured to release the heat radiator from the pressure applied by the support pin.

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15. (Amended) A molding device for a semiconductor device comprising:

a mold which is capable of being opened or closed and is provided with a cavity for placing a semiconductor assembly which comprises a semiconductor chip secured to a die pad of a lead frame;

a resin injection port provided to the mold for injecting a resin into the cavity;

at least one support pin provided in the cavity such that the support pin is able to enter into or be pulled out of the cavity to come in contact with the semiconductor assembly in the cavity; and

an actuator which moves the support pin in a direction of the axis of the support pin such that during injecting the resin into the cavity the support pin applies a pressure to the semiconductor assembly so as to cause a stress in the lead frame and such that the support pin releases the semiconductor assembly from the pressure applied by the support pin after the resin is injected before the resin is cured.

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24. (Amended) The molding device for a semiconductor device as defined in claim 15,

wherein the support pin is provided substantially on the axis of the resin injection port; and

wherein the support pin is placed at a position corresponding to a suspension lead which connects the die pad to a frame of the lead frame.

REMARKS

Claims 1-9, 11-18, 20-22, 24-27, 29 and 30 are pending. By this Amendment, claims 10, 19, 23 and 28 are cancelled, the specification and claims 1, 5, 11, 12, 15 and 24 are amended and Fig. 2 is corrected pursuant to the attached Request for Approval of Drawing Corrections.

The attached Appendix includes marked-up copies of each rewritten paragraph (37 C.F.R. §1.121(b)(1)(iii)) and claim (37 C.F.R. §1.121(c)(1)(ii)).

Reconsideration based on the following remarks is respectfully requested.

I. The Specification Satisfies All Formal Requirements

The Office Action objects to the disclosure based on informalities. Fig. 2 is corrected pursuant to the attached Request for Approval of Drawing Corrections to obviate this objection. Withdrawal of the objection to the disclosure is respectfully requested.

II. The Claims Satisfy the Requirements of 35 U.S.C. §112, Second Paragraph

The Office Action rejects claims 1, 3-4, 12, 14 and 24 under 35 U.S.C. §112, second paragraph as being indefinite. The drawings are corrected and claim 5 is amended to obviate this rejection. Withdrawal of the rejection under 35 U.S.C. §112, second paragraph is respectfully requested.